

SN54ALS74A, SN54AS74A, SN74ALS74A, SN74AS74A DUAL POSITIVE-EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH CLEAR AND PRESET

SDAS143C – APRIL 1982 – REVISED AUGUST 1995

- Package Options Include Plastic Small-Outline (D) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

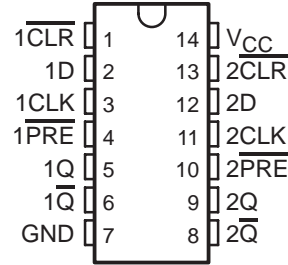
TYPE	TYPICAL MAXIMUM CLOCK FREQUENCY ($C_L = 50$ pF) (MHz)	TYPICAL POWER DISSIPATION PER FLIP-FLOP (mW)
'ALS74A	50	6
'AS74A	134	26

description

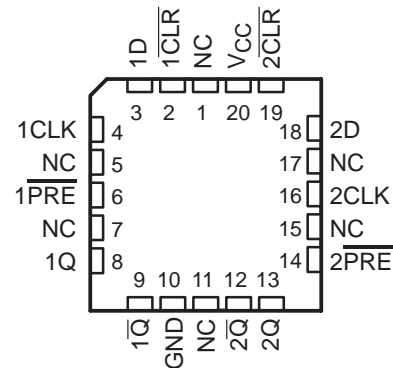
These devices contain two independent positive-edge-triggered D-type flip-flops. A low level at the preset (\overline{PRE}) or clear (\overline{CLR}) inputs sets or resets the outputs regardless of the levels of the other inputs. When \overline{PRE} and \overline{CLR} are inactive (high), data at the data (D) input meeting the setup-time requirements are transferred to the outputs on the positive-going edge of the clock (CLK) pulse. Clock triggering occurs at a voltage level and is not directly related to the rise time of CLK. Following the hold-time interval, data at the D input can be changed without affecting the levels at the outputs.

The SN54ALS74A and SN54AS74A are characterized for operation over the full military temperature range of -55°C to 125°C . The SN74ALS74A and SN74AS74A are characterized for operation from 0°C to 70°C .

SN54ALS74A, SN54AS74A . . . J PACKAGE
SN74ALS74A, SN74AS74A . . . D OR N PACKAGE
(TOP VIEW)



SN54ALS74A, SN54AS74A . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

FUNCTION TABLE

INPUTS				OUTPUTS	
\overline{PRE}	\overline{CLR}	CLK	D	Q	\overline{Q}
L	H	X	X	H	L
H	L	X	X	L	H
L	L	X	X	H^\dagger	H^\dagger
H	H	\uparrow	H	H	L
H	H	\uparrow	L	L	H
H	H	L	X	Q_0	\overline{Q}_0

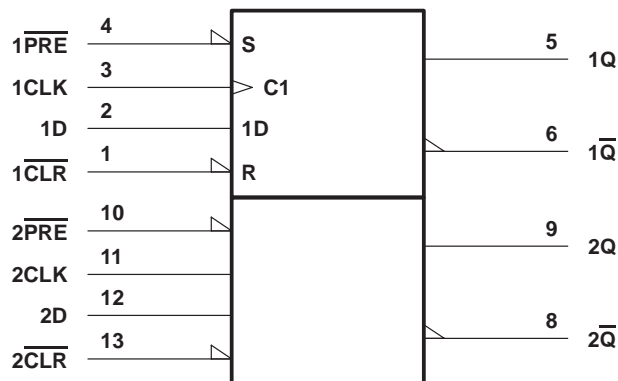
† The output levels in this configuration are not specified to meet the minimum levels for V_{OH} if the lows at \overline{PRE} and \overline{CLR} are near V_{IL} maximum. Furthermore, this configuration is nonstable; that is, it does not persist when \overline{PRE} or \overline{CLR} returns to its inactive (high) level.

SN54ALS74A, SN54AS74A, SN74ALS74A, SN74AS74A

DUAL POSITIVE-EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH CLEAR AND PRESET

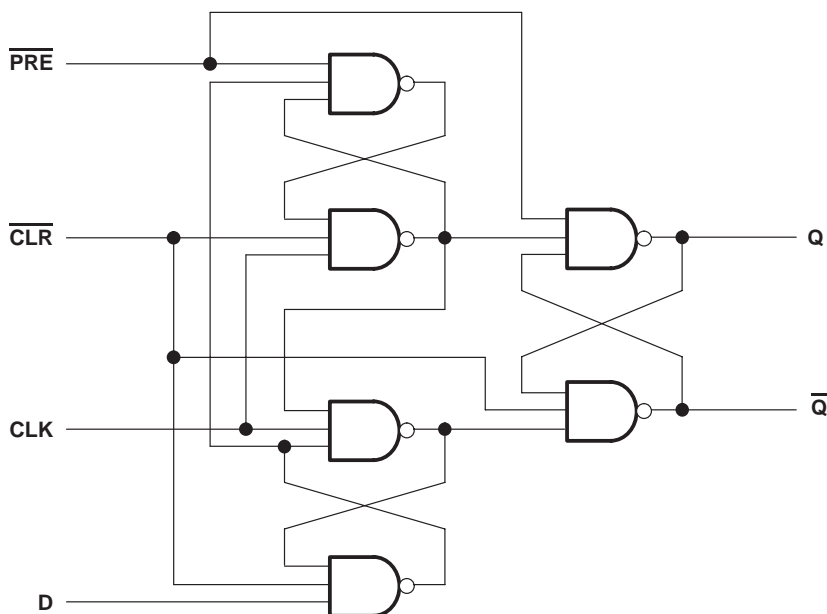
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logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the D, J, and N packages.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage, V_{CC}	7 V
Input voltage, V_I	7 V
Operating free-air temperature range, T_A : SN54ALS74A	–55°C to 125°C
SN74ALS74A	0°C to 70°C
Storage temperature range	–65°C to 150°C

‡ Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

SN54ALS74A, SN54AS74A, SN74ALS74A, SN74AS74A DUAL POSITIVE-EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH CLEAR AND PRESET

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recommended operating conditions

			SN54ALS74A			SN74ALS74A			UNIT		
			MIN	NOM	MAX	MIN	NOM	MAX			
V _{CC}	Supply voltage		4.5	5	5.5	4.5	5	5.5	V		
V _{IH}	High-level input voltage		2			2			V		
V _{IL}	Low-level input voltage		0.7			0.8			V		
I _{OH}	High-level output current		−0.4			−0.4			mA		
I _{OL}	Low-level output current		4			8			mA		
f _{clock}	Clock frequency		0	25		0	34		MHz		
t _w	Pulse duration	$\overline{\text{PRE}}$ or $\overline{\text{CLR}}$ low	15			15			ns		
		CLK high	17.5			14.5					
		CLK low	17.5			14.5					
t _{su}	Setup time before CLK↑	Data	16			15			ns		
		$\overline{\text{PRE}}$ or $\overline{\text{CLR}}$ inactive	10			10					
t _h	Hold time after CLK↑	Data	2			0			ns		
T _A	Operating free-air temperature		−55			125			0	70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		SN54ALS74A		SN74ALS74A		UNIT
				MIN	TYP†	MAX	MIN	
V _{IK}		V _{CC} = 4.5 V, I _I = -18 mA		-1.5		-1.5		V
V _{OH}		V _{CC} = 4.5 V to 5.5 V, I _{OH} = -2 mA		V _{CC} -2		V _{CC} -2		V
V _{OL}		V _{CC} = 4.5 V	I _{OL} = 4 mA	0.25	0.4	0.25	0.4	V
			I _{OL} = 8 mA			0.35	0.5	
I _I	CLK or D	V _{CC} = 4.5 V, V _I = 7 V		0.1	0.1		mA	
	$\overline{\text{PRE}}$ or $\overline{\text{CLR}}$			0.2	0.2			
I _{IH}	CLK or D	V _{CC} = 4.5 V, V _I = 2.7 V		20	20		μA	
	$\overline{\text{PRE}}$ or $\overline{\text{CLR}}$			40	40			
I _{IL}	CLK or D	V _{CC} = 4.5 V, V _I = 0.4 V		-0.2	-0.2		mA	
	$\overline{\text{PRE}}$ or $\overline{\text{CLR}}$			-0.4	-0.4			
I _O ‡		V _{CC} = 5.5 V, V _O = 2.25 V		-20	-112	-30	-112	mA
I _{CC}		V _{CC} = 5.5 V, See Note 1		2.4	4	2.4	4	mA

† All typical values are at $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$.

‡ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS} .

NOTE 1: I_{CC} is measured with D, CLK, and \overline{PRE} grounded, then with D, CLK, and \overline{CLR} grounded.



SN54ALS74A, SN54AS74A, SN74ALS74A, SN74AS74A

DUAL POSITIVE-EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH CLEAR AND PRESET

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switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 4.5 V to 5.5 V, C _L = 50 pF, R _L = 500 Ω, T _A = MIN to MAX†				UNIT
			SN54ALS74A		SN74ALS74A		
			MIN	MAX	MIN	MAX	
f _{max}			25		34		MHz
t _{PLH}	$\overline{\text{PRE}}$ or $\overline{\text{CLR}}$	Q or $\overline{\text{Q}}$	3	18	3	13	ns
t _{PHL}			5	17	5	15	
t _{PLH}	CLK	Q or $\overline{\text{Q}}$	5	23	5	16	ns
t _{PHL}			5	20	5	18	

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage, V _{CC}	7 V
Input voltage, V _I	7 V
Operating free-air temperature range, T _A : SN54AS74A	–55°C to 125°C
SN74AS74A	0°C to 70°C
Storage temperature range	–65°C to 150°C

‡ Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

			SN54AS74A			SN74AS74A			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	
V _{CC}	Supply voltage		4.5	5	5.5	4.5	5	5.5	V
V _{IH}	High-level input voltage		2			2			V
V _{IL}	Low-level input voltage				0.8			0.8	V
I _{OH}	High-level output current				–2			–2	mA
I _{OL}	Low-level output current				20			20	mA
f _{clock} *	Clock frequency		0		90	0		105	MHz
t _w *	Pulse duration	$\overline{\text{PRE}}$ or $\overline{\text{CLR}}$ low	4			4			ns
		CLK high	4			4			
		CLK low	5.5			5.5			
t _{su} *	Setup time before CLK↑	Data	4.5			4.5			ns
		$\overline{\text{PRE}}$ or $\overline{\text{CLR}}$ inactive	2			2			
t _h *	Hold time after CLK↑	Data	0			0			ns
T _A	Operating free-air temperature		–55		125	0		70	°C

* On products compliant to MIL-STD-833, Class B, this parameter is based on characterization data but is not production tested.



SN54ALS74A, SN54AS74A, SN74ALS74A, SN74AS74A

DUAL POSITIVE-EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH CLEAR AND PRESET

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	SN54AS74A			SN74AS74A			UNIT
			MIN	TYP†	MAX	MIN	TYP†	MAX	
V_{IK}		$V_{CC} = 4.5\text{ V}$, $I_I = -18\text{ mA}$			-1.2			-1.2	V
V_{OH}		$V_{CC} = 4.5\text{ V to } 5.5\text{ V}$, $I_{OH} = -2\text{ mA}$	$V_{CC}-2$			$V_{CC}-2$			V
V_{OL}		$V_{CC} = 4.5\text{ V}$, $I_{OL} = 20\text{ mA}$		0.25	0.5		0.25	0.5	V
I_I		$V_{CC} = 5.5\text{ V}$, $V_I = 7\text{ V}$			0.1			0.1	mA
I_{IH}	CLK or D	$V_{CC} = 5.5\text{ V}$, $V_I = 2.7\text{ V}$			20			20	μA
	$\overline{\text{PRE}}$ or $\overline{\text{CLR}}$				40			40	
I_{IL}	CLK or D	$V_{CC} = 5.5\text{ V}$, $V_I = 0.4\text{ V}$			-0.5			-0.5	mA
	$\overline{\text{PRE}}$ or $\overline{\text{CLR}}$				-1.8			-1.8	
$I_{O\ddagger}$		$V_{CC} = 5.5\text{ V}$, $V_O = 2.25\text{ V}$	-30		-112	-30		-112	mA
I_{CC}		$V_{CC} = 5.5\text{ V}$, See Note 1		10.5	16		10.5	16	mA

† All typical values are at $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$.

‡ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS} .

NOTE 1: I_{CC} is measured with D, CLK, and $\overline{\text{PRE}}$ grounded, then with D, CLK, and $\overline{\text{CLR}}$ grounded.

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 4.5 V to 5.5 V, C _L = 50 pF, R _L = 500 Ω, T _A = MIN to MAX§				UNIT
			SN54AS74A		SN74AS74A		
			MIN	MAX	MIN	MAX	
f _{max} *			90		105		MHz
t _{PLH}	PRE or CLR	Q or Q̄	2	9	2	7.5	ns
t _{PHL}			2.5	11.5	2.5	10.5	
t _{PLH}	CLK	Q or Q̄	2.5	10	3	8	ns
t _{PHL}			3.5	10.5	3	9	

* On products compliant to MIL-STD-883C, Class B, this parameter is based on characterization data but is not production tested.

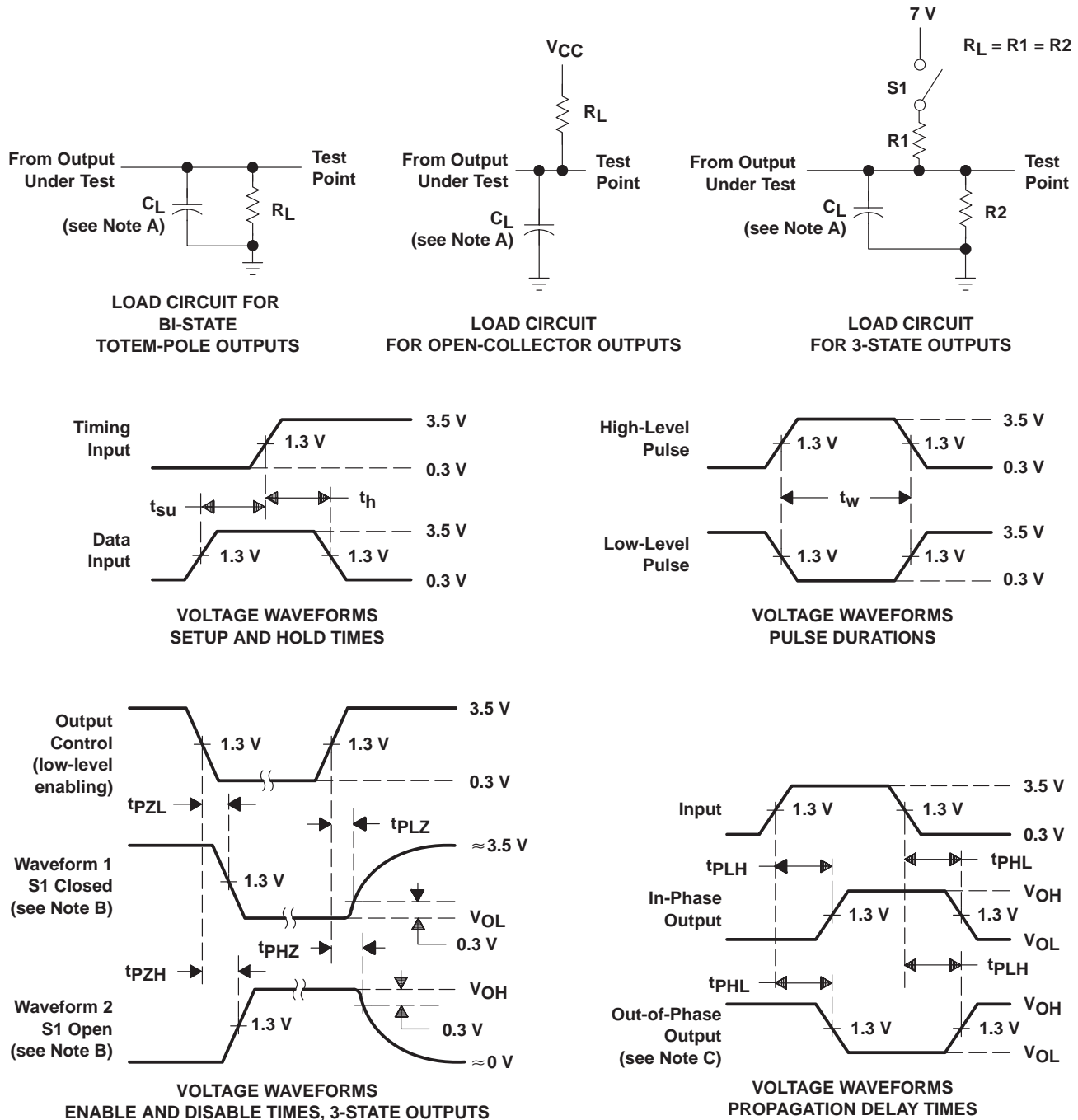
§ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



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PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
 D. All input pulses have the following characteristics: $PRR \leq 1$ MHz, $t_r = t_f = 2$ ns, duty cycle = 50%.
 E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
5962-9862701Q2A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Call TI	
5962-9862701QCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Call TI	
84011012A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Call TI	
8401101CA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Call TI	
8401101DA	ACTIVE	CFP	W	14	1	TBD	Call TI	Call TI	
JM38510/37101B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
JM38510/37101BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
M38510/37101B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
M38510/37101BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
SN54ALS74AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
SN54AS74AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
SN74ALS74AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS74ADE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS74ADG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS74ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS74ADRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS74ADRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS74AJ	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	
SN74ALS74AN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74ALS74AN3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	
SN74ALS74ANE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74ALS74ANSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS74ANSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
SN74ALS74ANSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS74AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS74ADE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS74ADG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS74ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS74ADRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS74ADRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS74AN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74AS74ANE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74AS74ANSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS74ANSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS74ANSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SNJ54ALS74AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
SNJ54ALS74AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
SNJ54ALS74AW	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	
SNJ54AS74AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
SNJ54AS74AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF SN54ALS74A, SN54AS74A, SN74ALS74A, SN74AS74A :

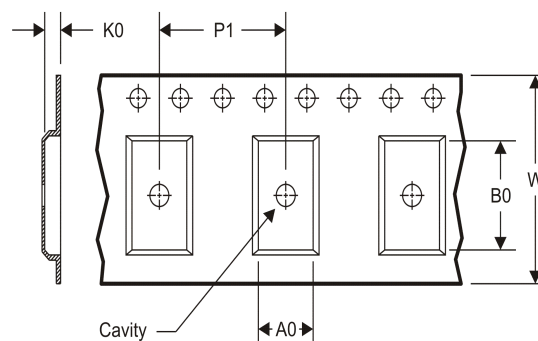
● Catalog: [SN74ALS74A](#), [SN74AS74A](#)

● Military: [SN54ALS74A](#), [SN54AS74A](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS74ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74ALS74ANSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74AS74ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74AS74ANSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



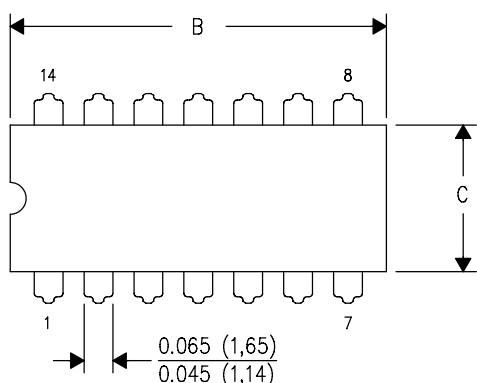
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS74ADR	SOIC	D	14	2500	367.0	367.0	38.0
SN74ALS74ANSR	SO	NS	14	2000	367.0	367.0	38.0
SN74AS74ADR	SOIC	D	14	2500	367.0	367.0	38.0
SN74AS74ANSR	SO	NS	14	2000	367.0	367.0	38.0

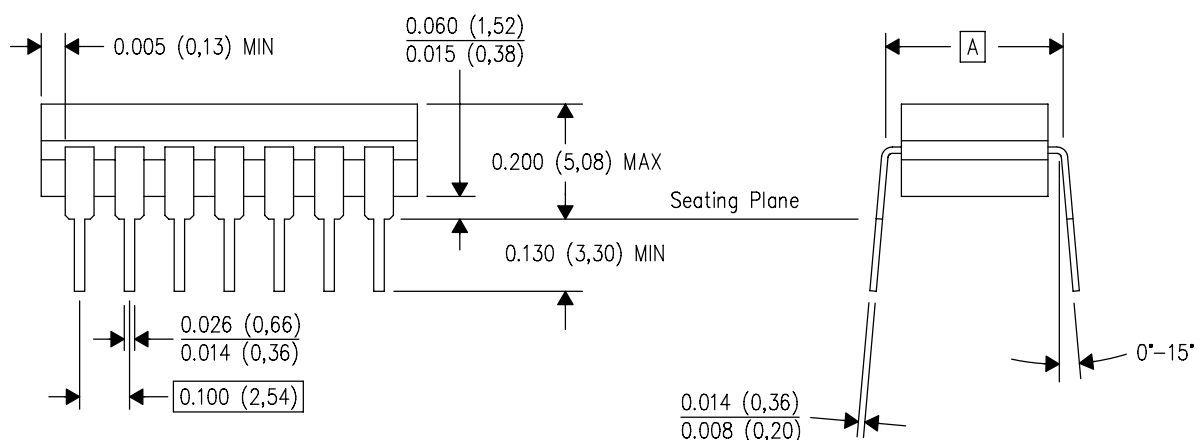
J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

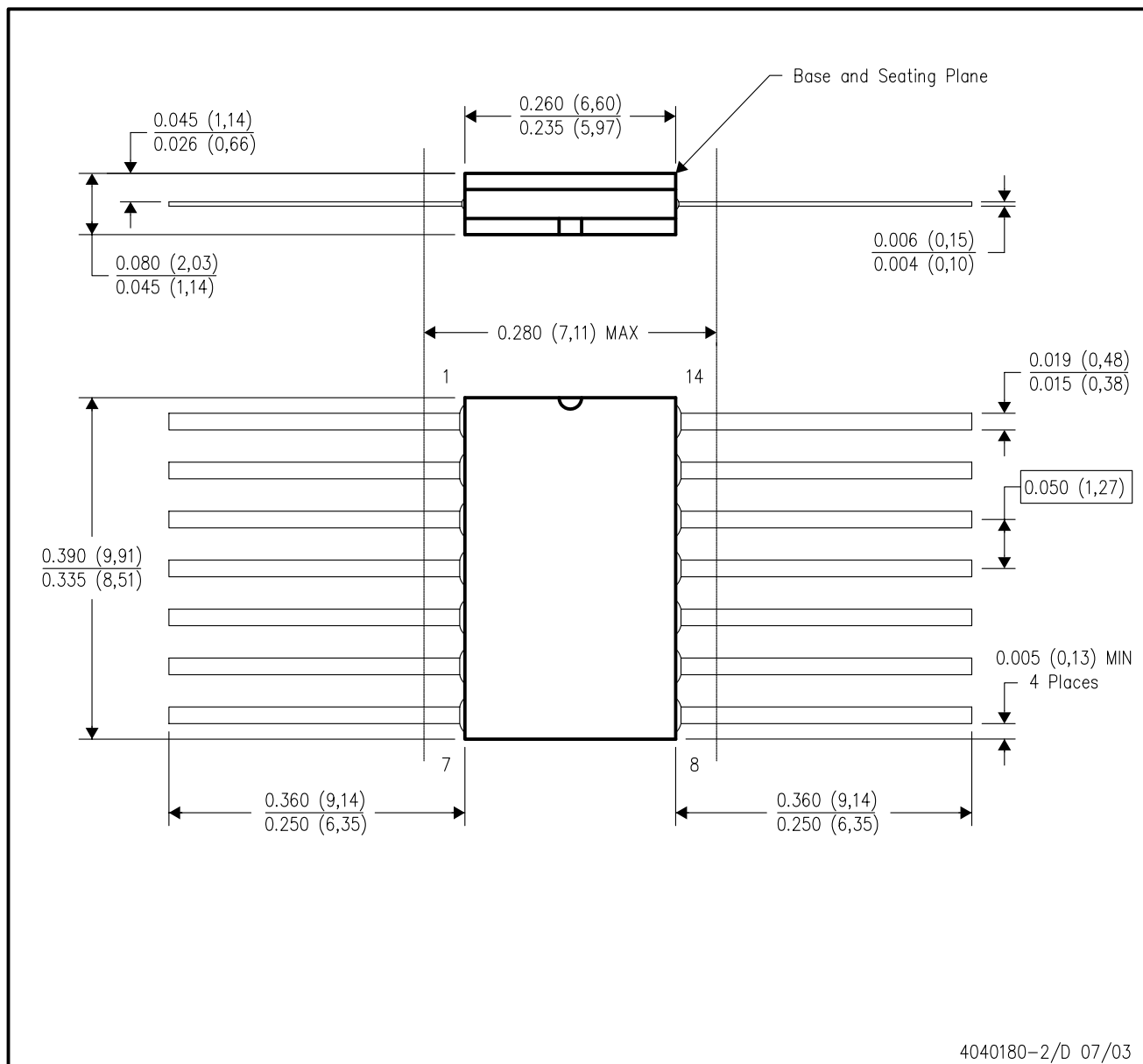


4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK

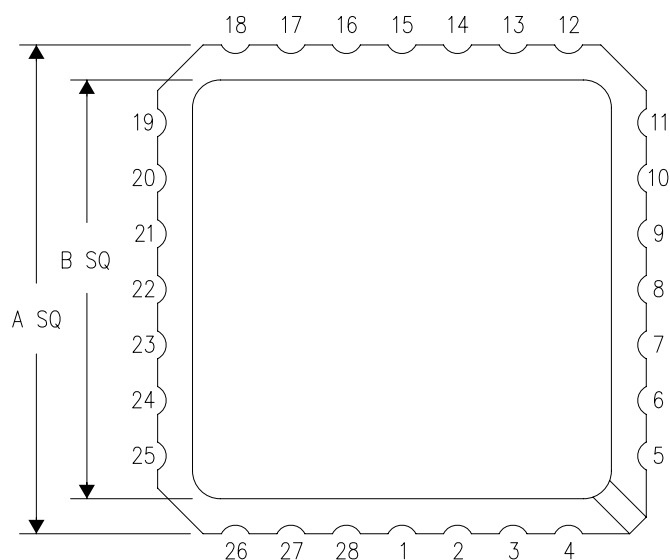


- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only.
 - Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB

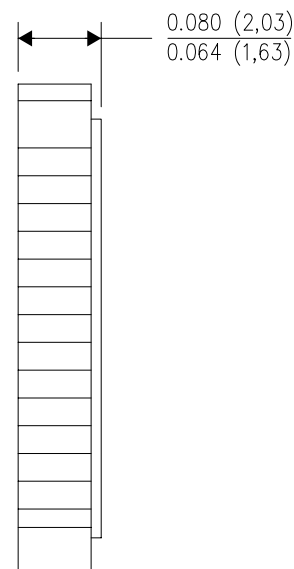
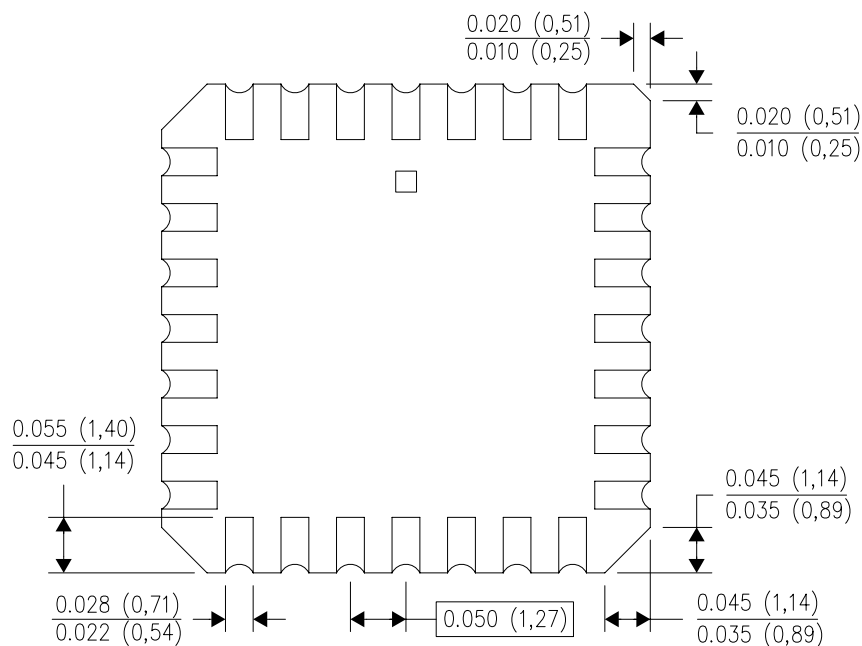
FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



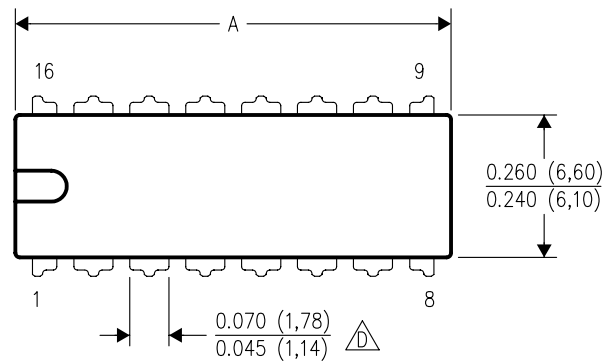
4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a metal lid.
 - Falls within JEDEC MS-004

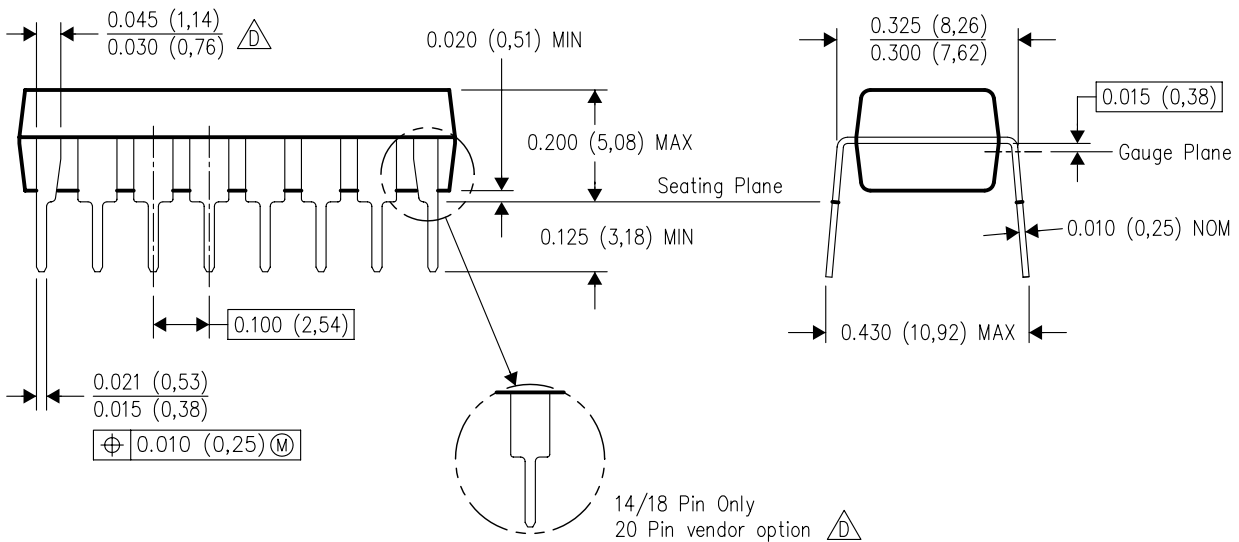
N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



PINS **	14	16	18	20
DIM				
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



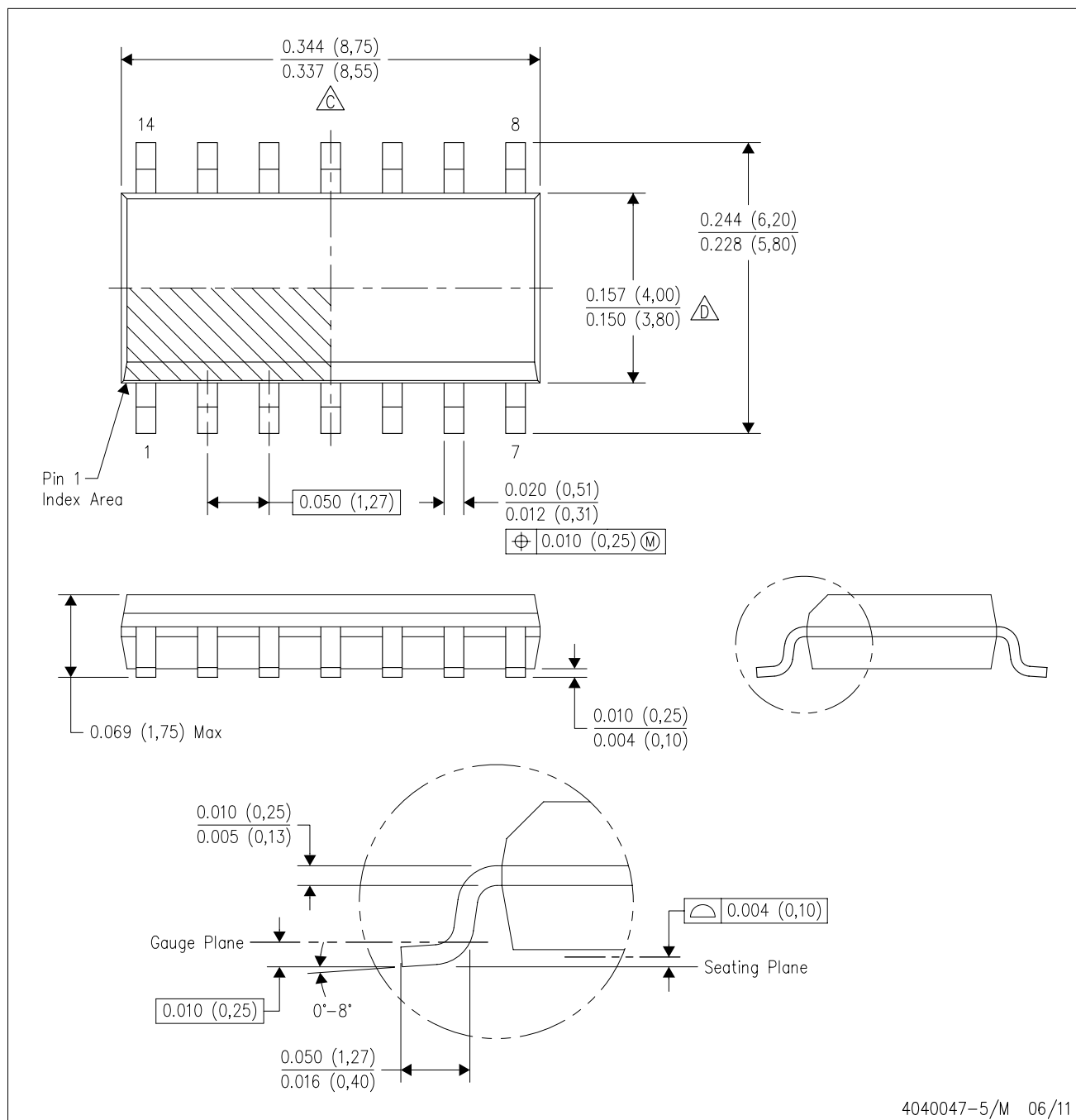
14/18 Pin Only
20 Pin vendor option

4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE

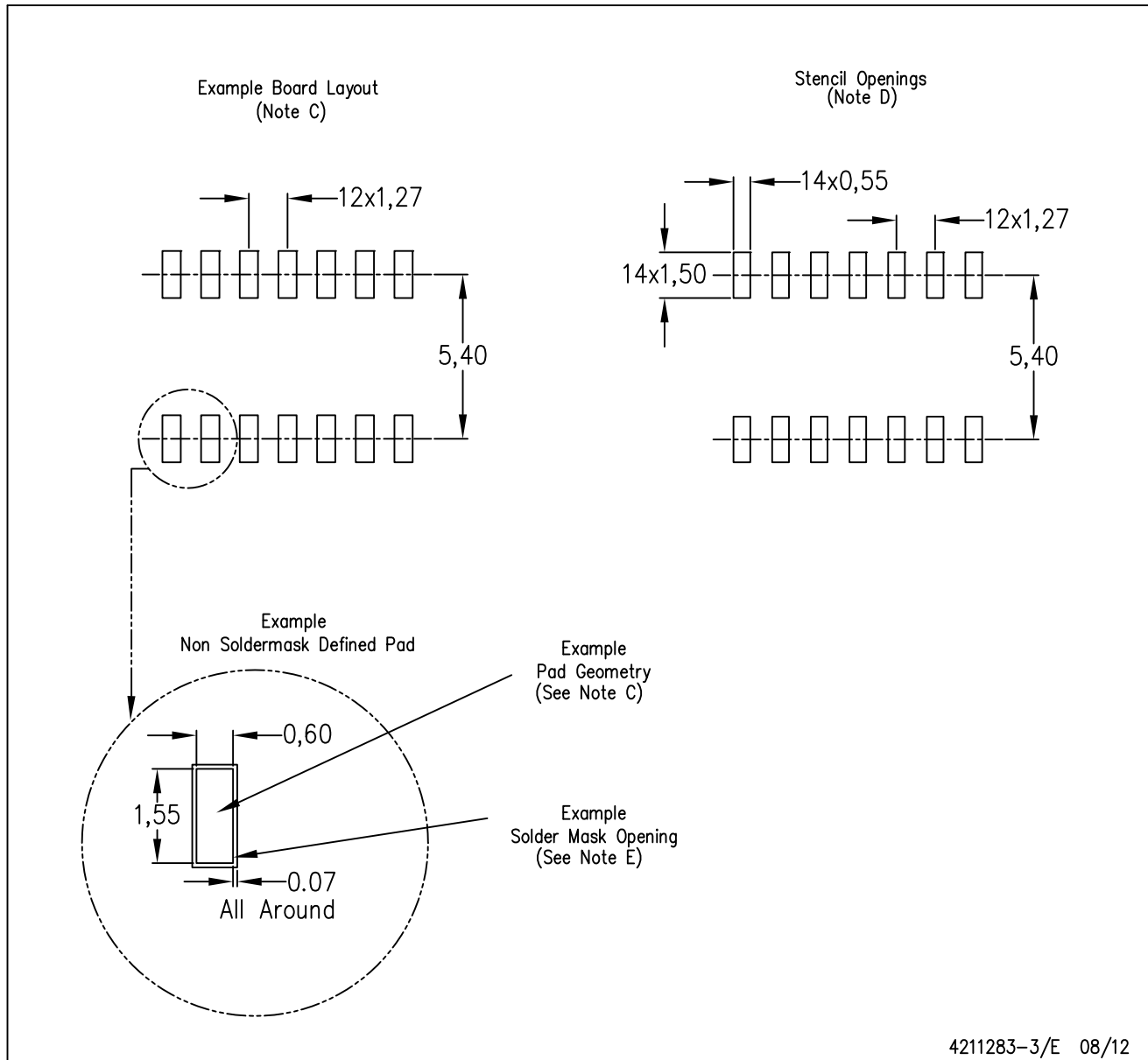


NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



4211283-3/E 08/12

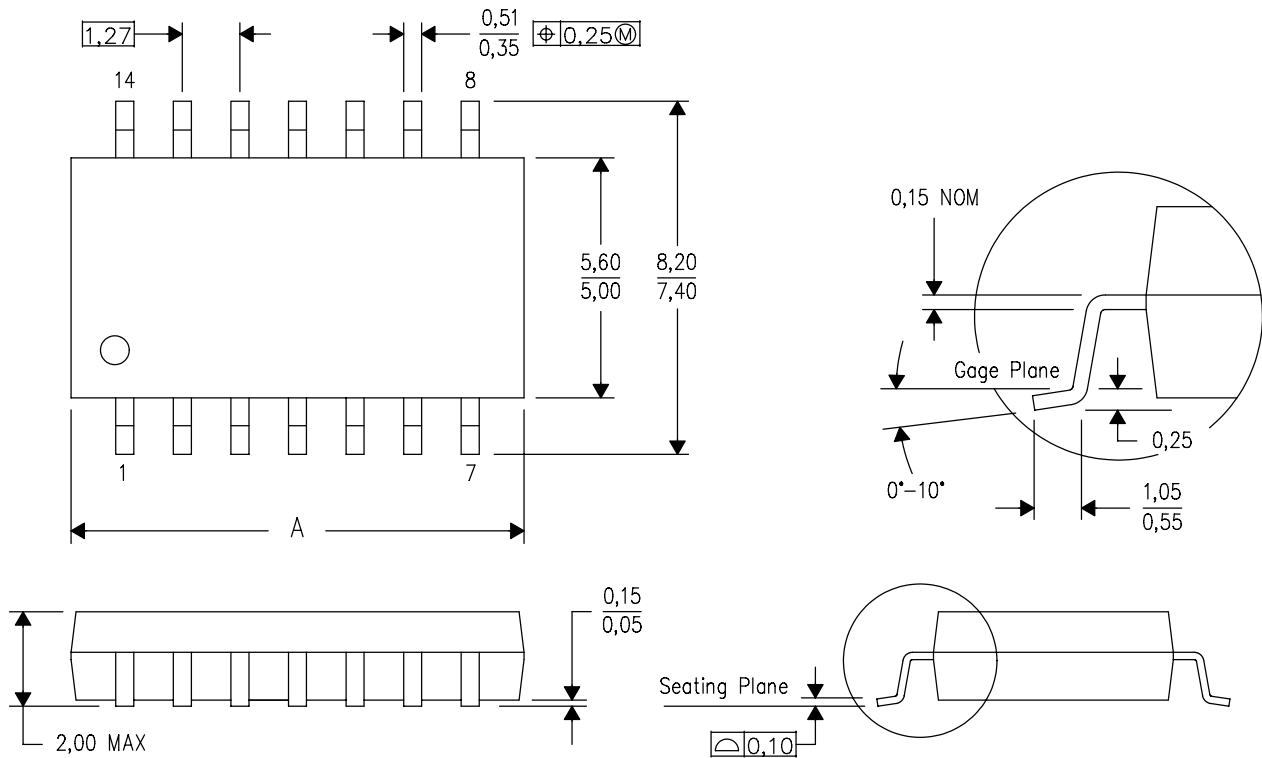
- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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